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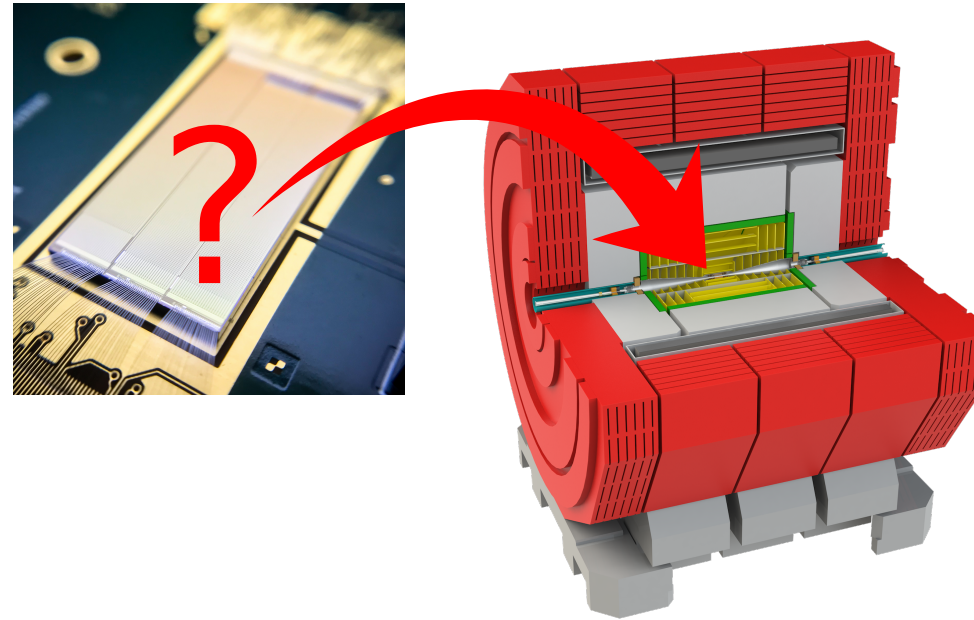


GEFÖRDERT VOM
Bundesministerium
für Bildung
und Forschung



Silicon Pixel Detector R&D

for Future HEP Experiments



18th Wolfgang Gentner Day
CERN, October 28th, 2020

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Heidelberg University & CERN

supervisors:
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Dr. Dominik Dannheim (CERN)

The Future of HEP

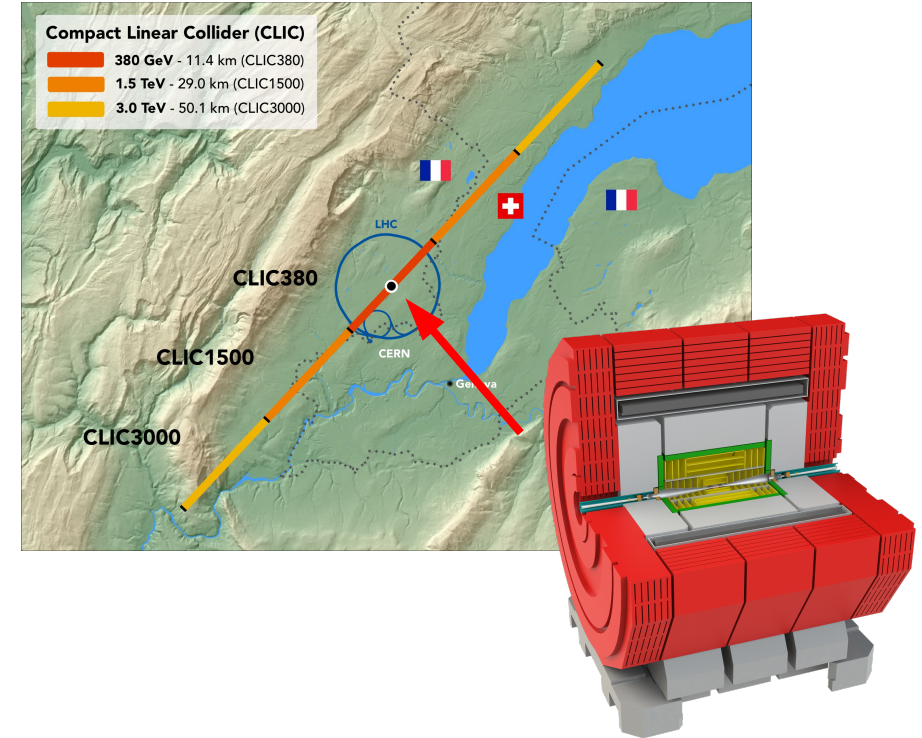


and then?

• circular?



• linear?



Compact Linear Collider

- $e^+ e^-$ with energies up to 3 TeV
- up to 50 km long
→ construction in 3 stages
- precision Higgs + top physics + BSM

We don't know yet...but for all:

→ stringent detector requirements

→ extensive R&D needed

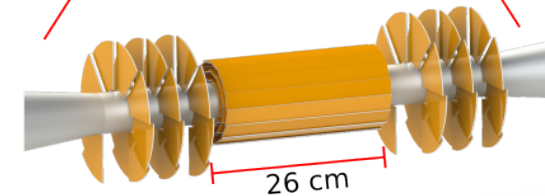
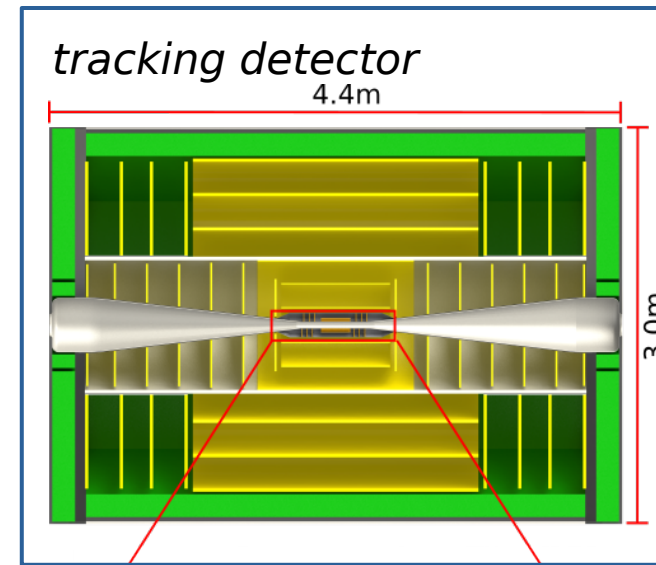
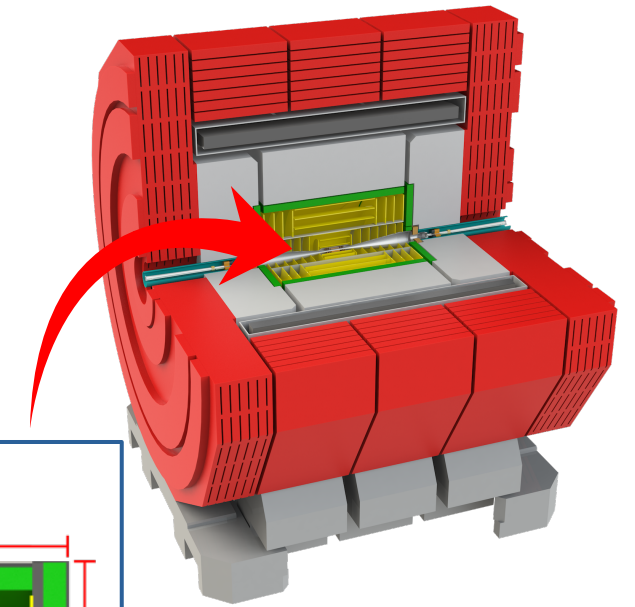


- detector requirements

- **triggerless readout**
in 20 ms gaps between bunch trains
- timing resolution: **~ 5 ns**
- hit detection efficiency: **99.7-99.9%**
- low radiation exposure

Tracking Detector

- ~140 m² silicon
- spatial resolution: **~ 7 μm** (transversal)
- max. granularity: **1-10 mm** pixel size (long.)
- material budget: **~ 1-1.5 % X₀/layer**



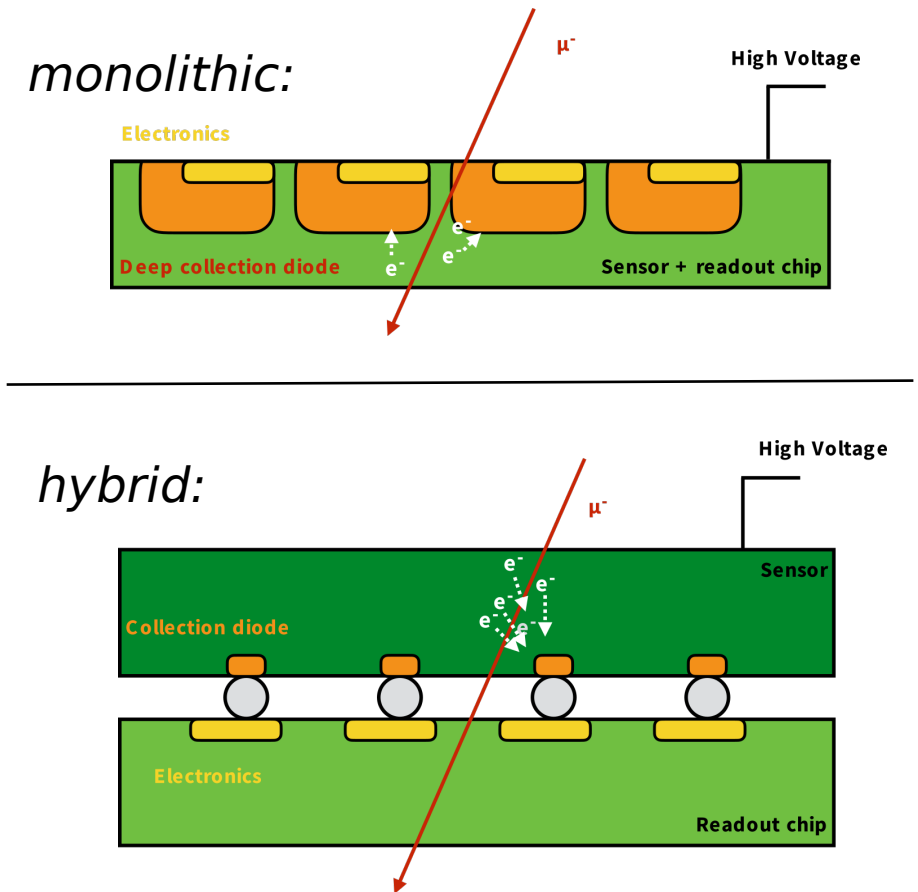
vertex detector

see also [CLICdp-Note-2017-002](#)

HV-MAPS - the technology

High Voltage Monolithic Active Pixel Sensors:

- **active**
 - in-pixel amplifier
- **monolithic**
 - signal generation + readout integrated in single chip (↔ hybrid sensor)
 - **low material budget**
- **high voltage**
 - O(100V) bias voltage
 - **fast** charge collection via drift (↔ diffusion)
 - large depleted volume → **large signal**



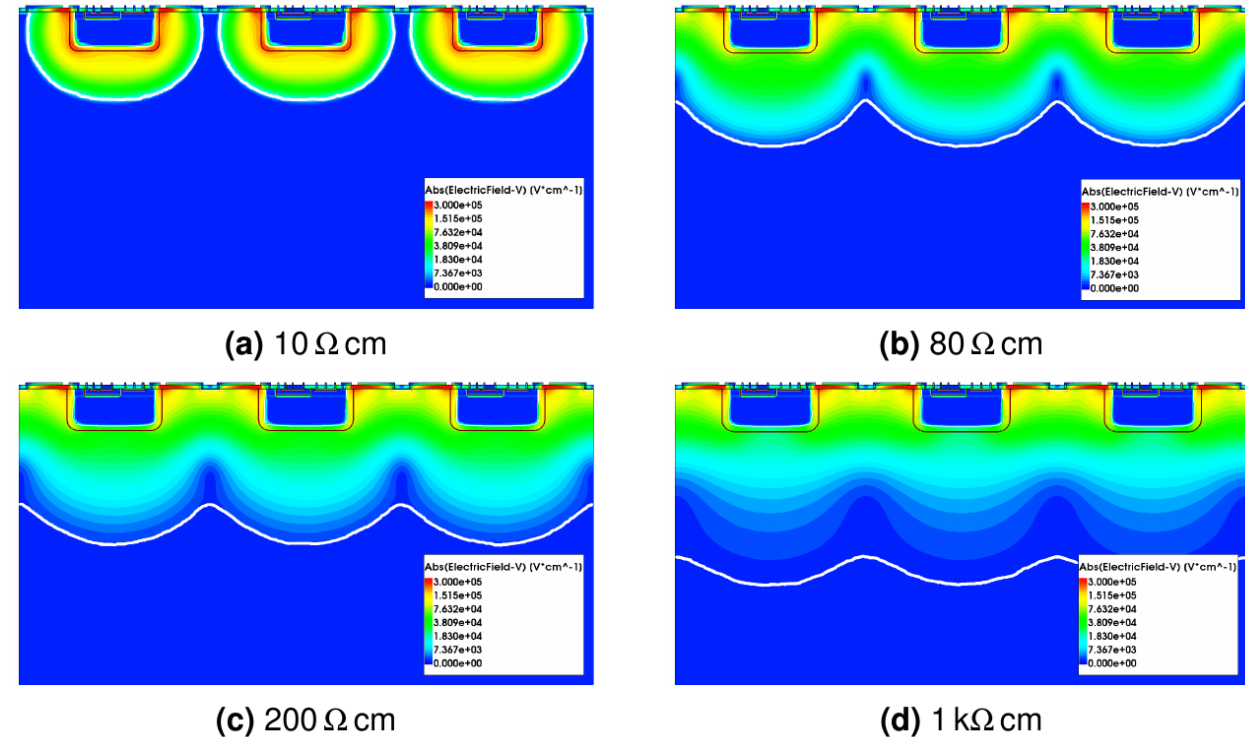
HV-MAPS with large collection electrodes

- intrinsic **radiation hardness**
- large depleted volume
→ **large signal**
- uniform electric field
→ **uniform response**
(similar to planar sensor)

substrate resistivity ρ :

$$\text{Ohmic } R = \rho \cdot \frac{\text{length}}{\text{area}}$$

- higher resistivity → larger depleted volume for given high voltage

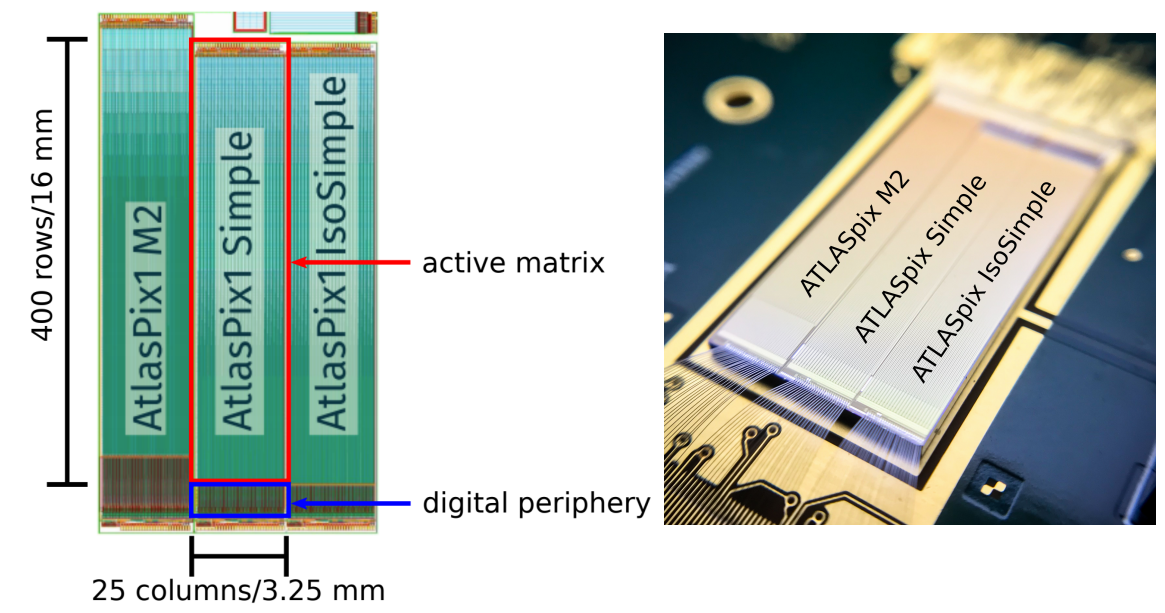
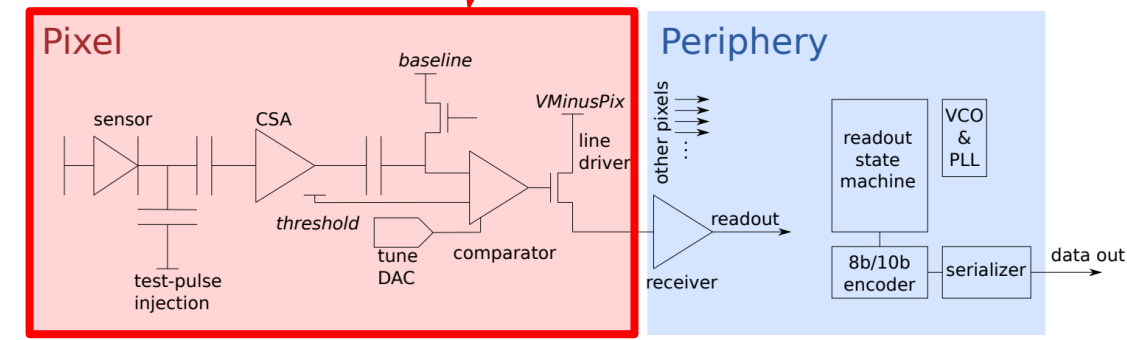
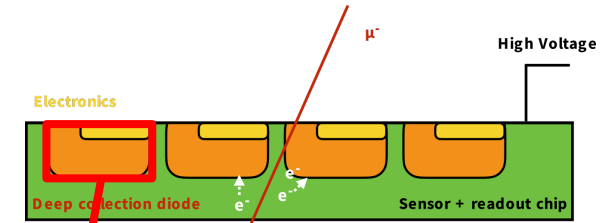


|Electric field| for **different substrate resistivities**
at same high voltage

The ATLASpix - an HV-MAPS example

- designed for
 - **ATLAS ITk** upgrade
 - **CLIC** tracking detector

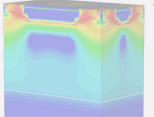
technology	180nm HV-CMOS
pixel matrix	25 columns x 400 rows
pixel size	130 x 40 μm^2
readout scheme	self-triggered/continuous
readout mode	time + energy (in each pixel)
substrate resistivity	20, 80, 200 Ωcm



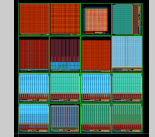
The Life Cycle of Prototyping

Early R&D

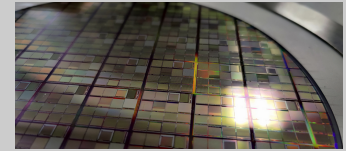
- TCAD simulations
- process optimization



Chip Design



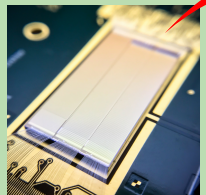
Manufacturing



not covered today

Commissioning

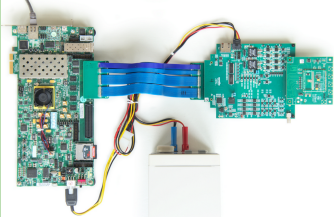
- integration into readout system



not covered today

Lab Characterization

- optimization of chip settings



Focus of today

Test-beam Characterization

- hit detection efficiency
- spatial + time resolution



Complementary Simulations

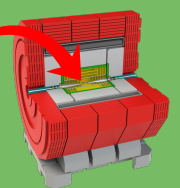
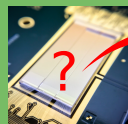
- telescope performance
- ...



Focus of today

Evaluation

- compare to specifications
- feedback to chip designers

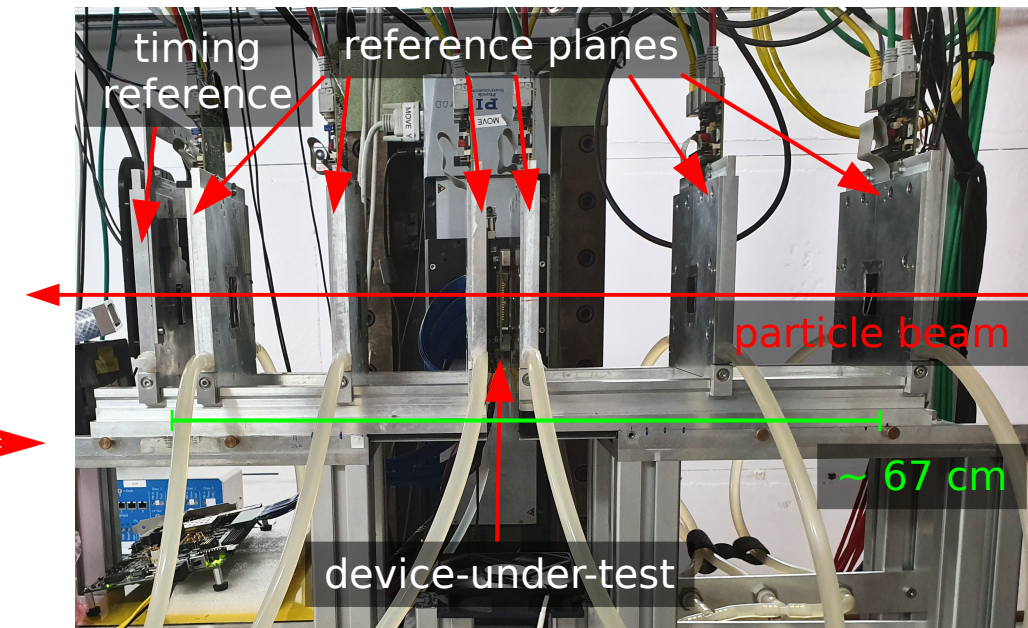
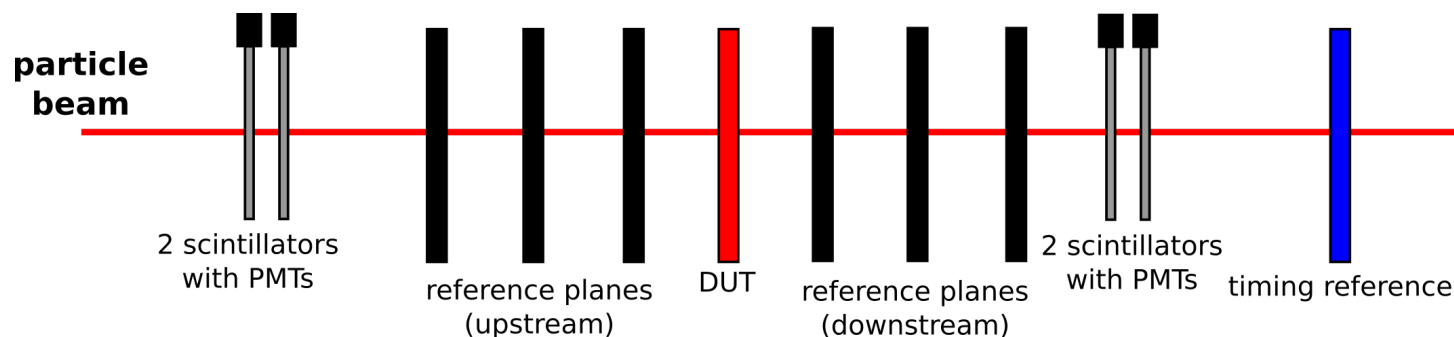


Test Beam Setup at DESY

DESY II test-beam facility
(Hamburg, Germany)



- reference detectors:
 - combine hits into **reference track** (incl. timestamp)
 - determine **precise intercept** with device-under-test (DUT)
- compare track with hits on DUT
 - spatial + time resolution
 - hit detection efficiency

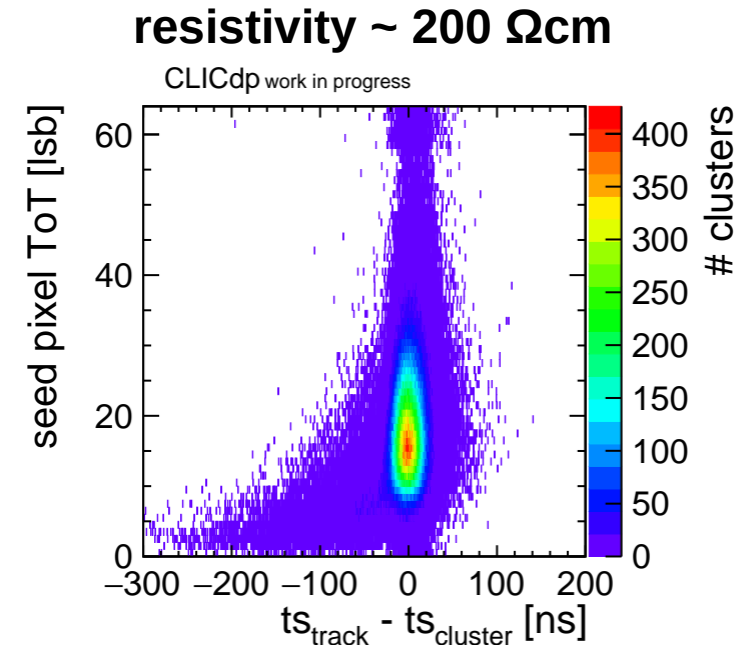
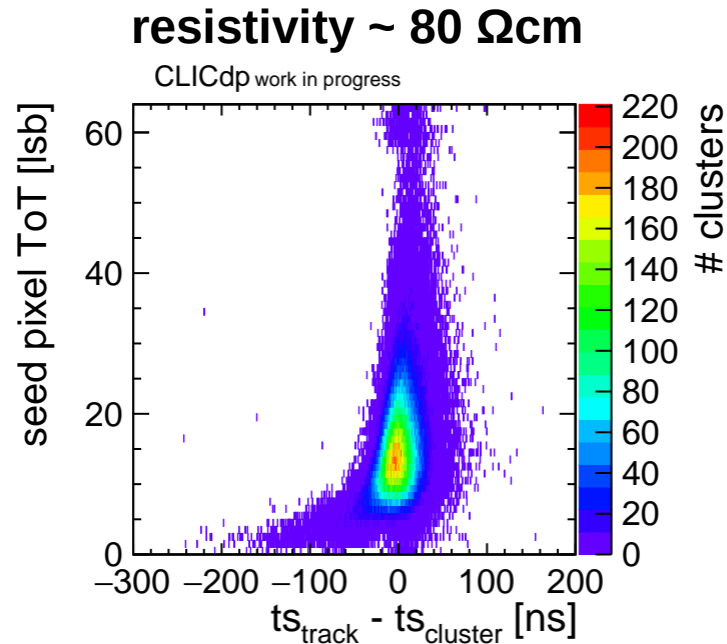
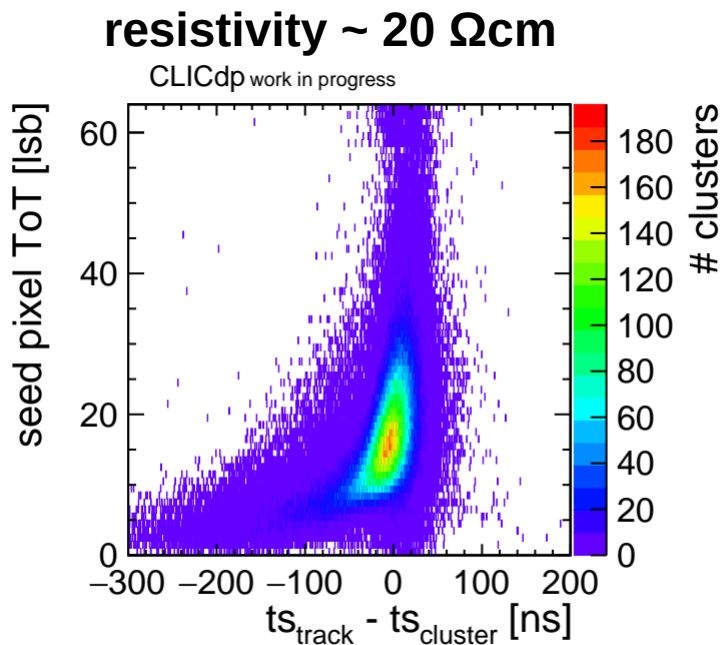
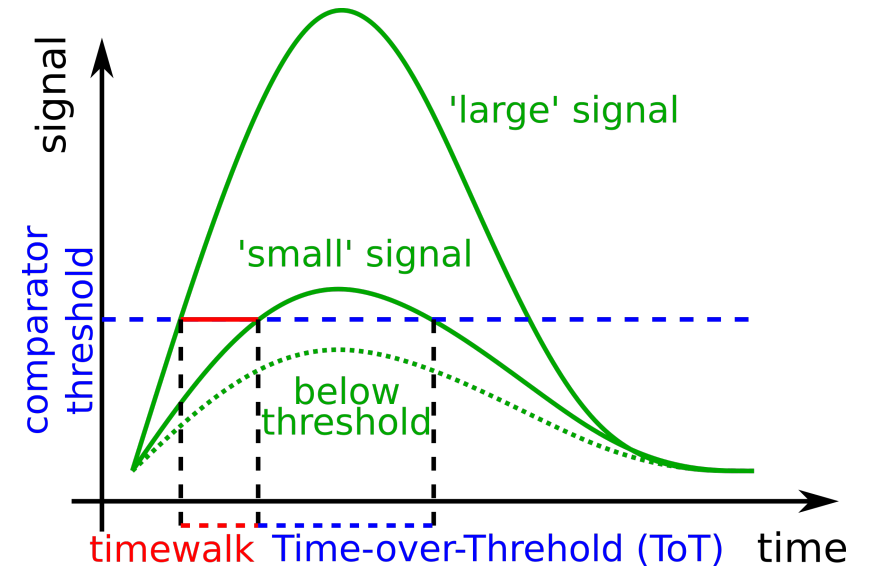


Some Example Results

from ATLASpix test-beam measurements

ATLASpix - timewalk

- comparing **different resistivities** at:
 - threshold $\sim 1080 e^-$
 - high voltage = -50 V
- clear dependence on resistivity



ATLASpix - timing performance

- comparing **different resistivities** at:

- threshold $\sim 650 e^-$
- high voltage = -50 V

- clear dependence on resistivity:

higher resistivity \rightarrow larger depleted volume
 \rightarrow higher signal/better S/N \rightarrow larger field
 \rightarrow faster charge collection/less timewalk

- after timewalk correction:

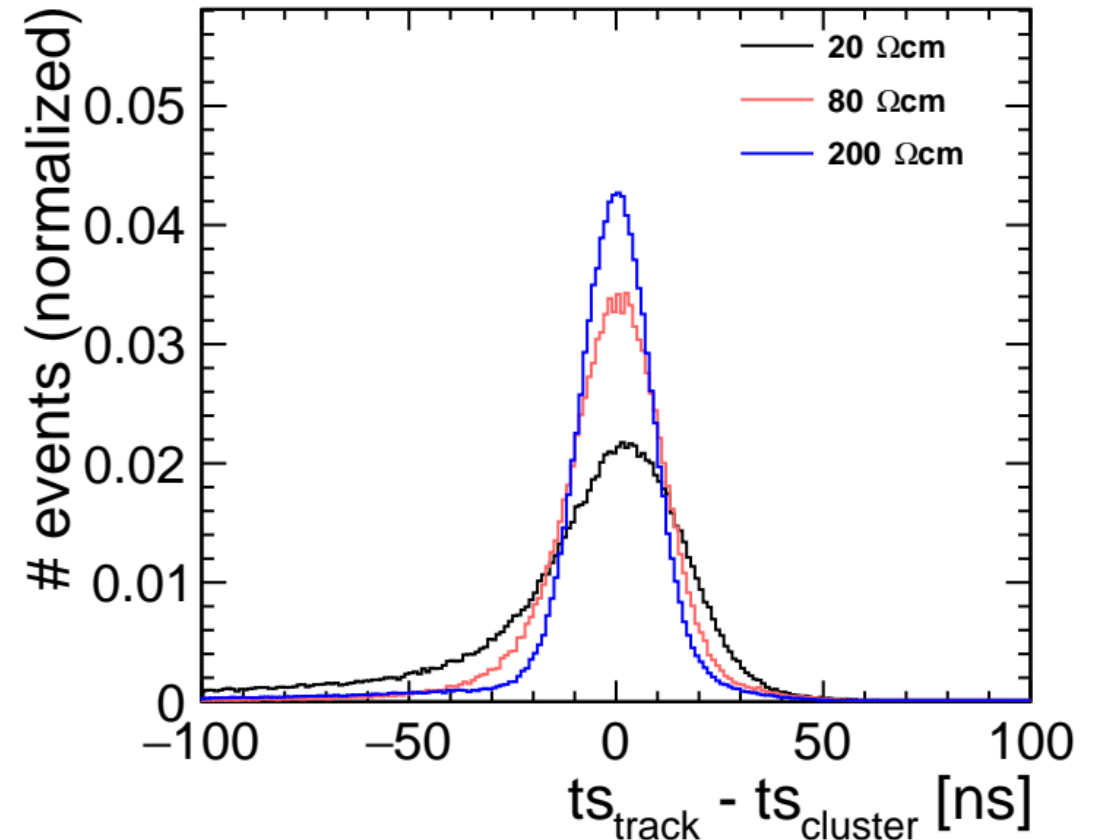
resistivity [Ωcm]	σ_{Gauss} [ns]
20	13.3
80	9.4
200	8.3

- **best result: $\sigma_{\text{Gauss}} = 6.8 \text{ ns}$**

(200 Ωcm , 100 μm , high voltage = -50V, threshold = 480 e^-)

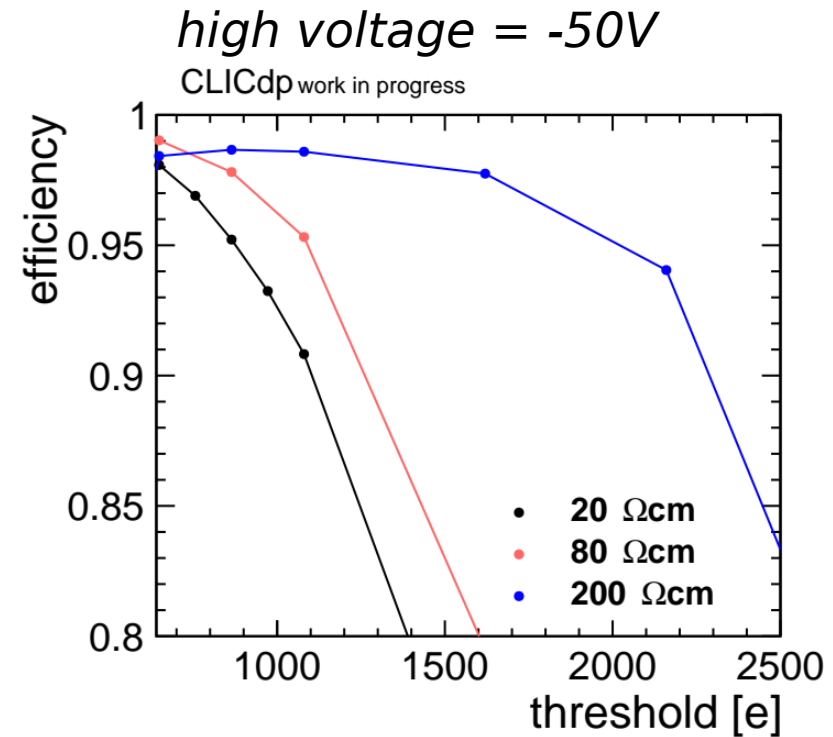
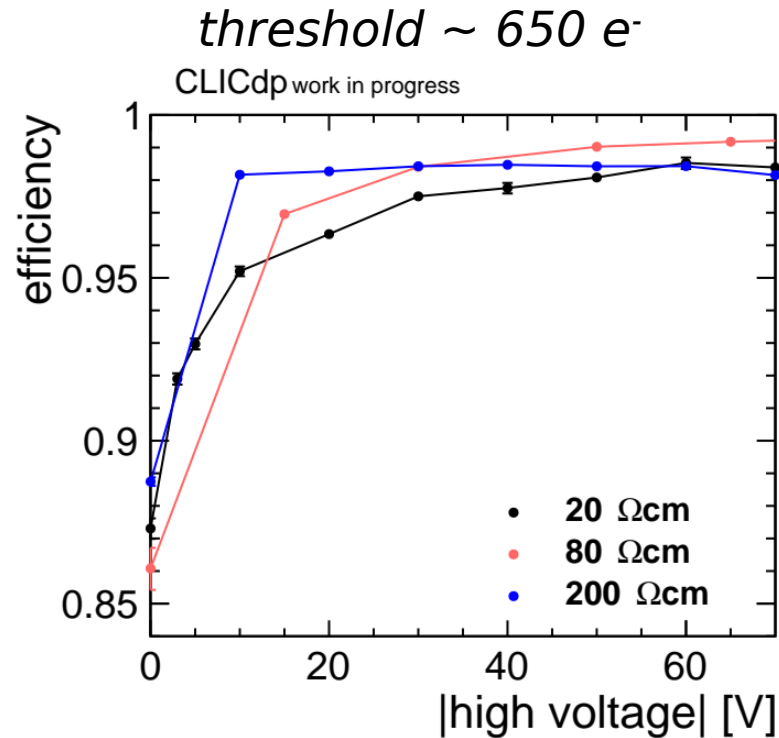
*time residuals for
different resistivities*

CLICdp work in progress



ATLASpix - hit detection efficiency

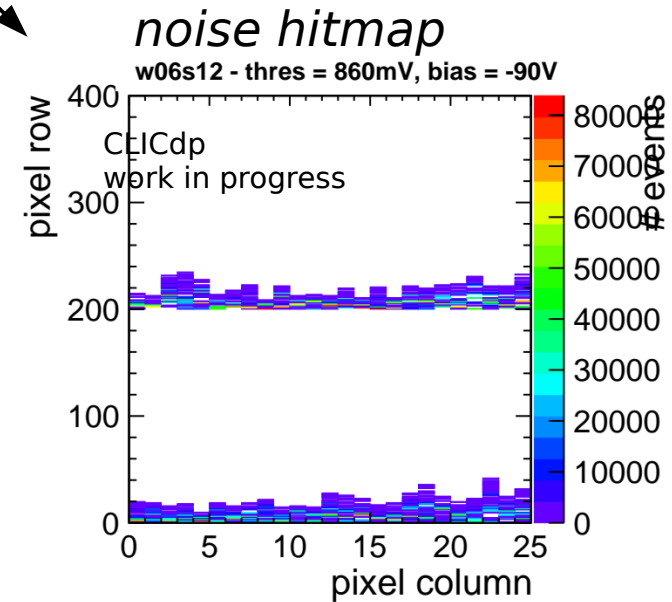
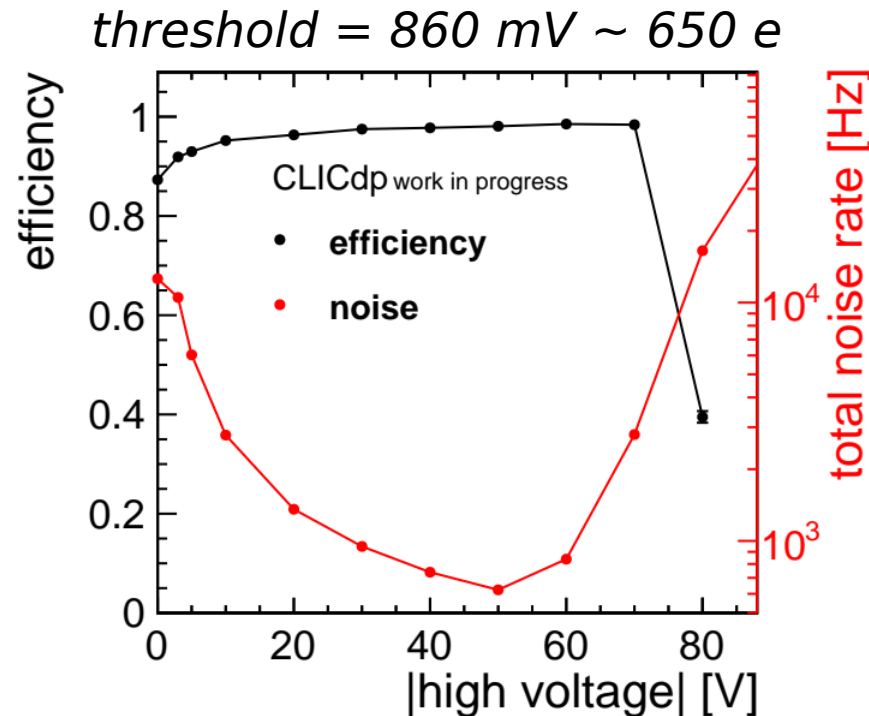
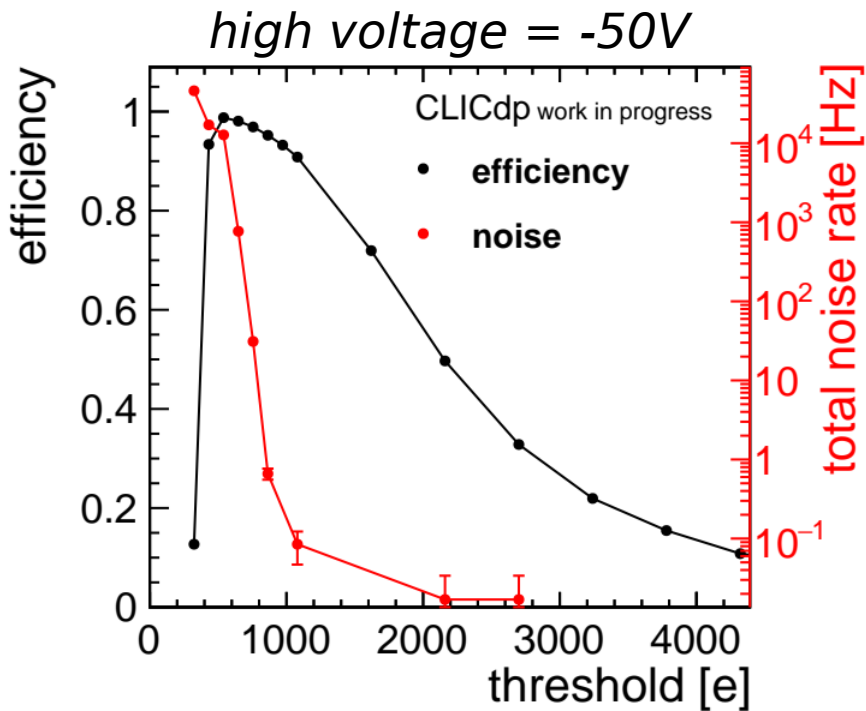
- comparing **different resistivities**
- efficiency peaks above $\sim 99\%$
- as expected: larger efficiency operating window at higher resistivities



ATLASpix - efficiency & noise

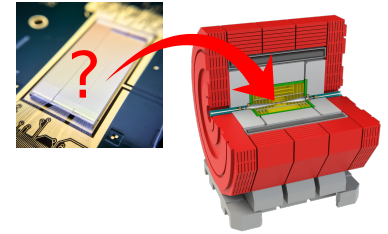
- here: sample with 20 Ωcm
- find balance
efficiency \leftrightarrow noise rate

- large bias/low threshold:
 - **over-saturated readout**



Comparison to the Requirements

of the CLIC Tracking Detector



Requirement

- spatial resolution
 - in y: $< 7 \mu\text{m}$ (RMS)
 - in x: 1-10 mm (pixel size)
- timing resolution
 - ~5 ns
- material budget
 - $< 200 \mu\text{m}$
- efficiency
 - $> 99.7\text{-}99.9\%$

ATLASpix


~11.3 μm
130 μm

6.8 ns
at $\sim 480e^-$ thres

62-100 μm
(50 μm possible)

$> 99.7\%$

→ new sensors

- with adapted pixel geometry + other improvements
- in collaboration with 
 - "MightyTracker"
 - (study for upgrade Ib and II)

	ATLASpix	new sensors:
	40 x 130 μm^2	25 x 165 μm^2
longitudinal	130 $\mu\text{m} \ll 1 \text{ mm}$	165 $\mu\text{m} \ll 1 \text{ mm}$
transversal (binary resolution)	40 $\mu\text{m}/\sqrt{12}$ ~ 11.5 μm	25 $\mu\text{m}/\sqrt{12}$ ~ 7.2 μm

↑
or better

→ overall **very good performance**

→ interesting technology for HEP

Summary & Outlook

- future HEP experiments:
 - very **stringent detector requirements**
- monolithic pixel sensors:
 - **HV-MAPS = promising technology** for future HEP applications (and beyond)

Acknowledgment:

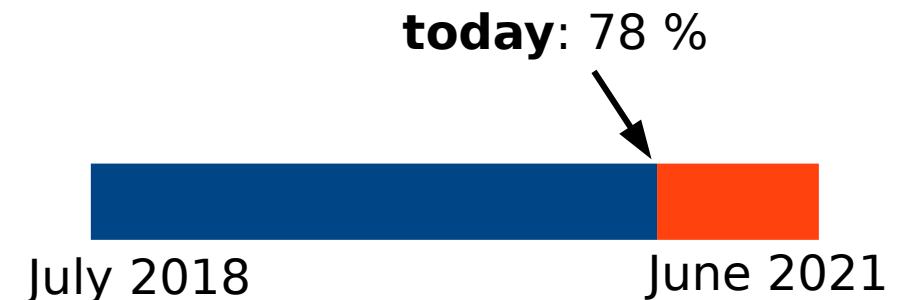
The measurements leading to these results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF).



What's next?

- rotation analysis
- x-ray calibration
- compare with new sensor

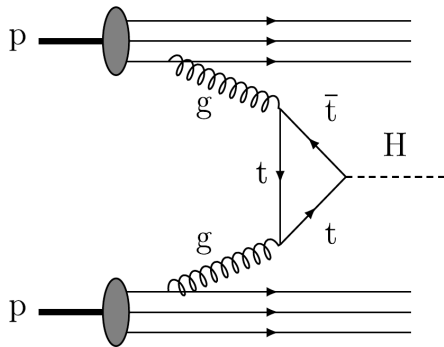
PhD progress:



Backup

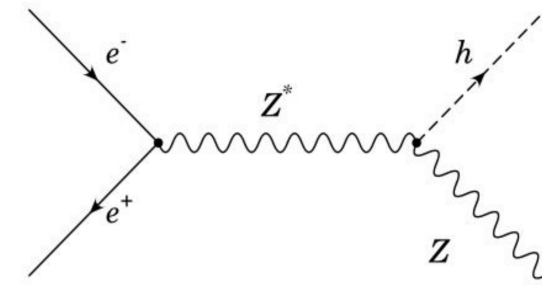
in case there are some questions...

Motivation for an e^+e^- collider



pp collisions

- protons = compound objects
 - event-by-event initial state unknown
→ limits achievable precision
- circular collider feasible
- high rates of QCD background
 - complex triggering schemes
 - high radiation levels

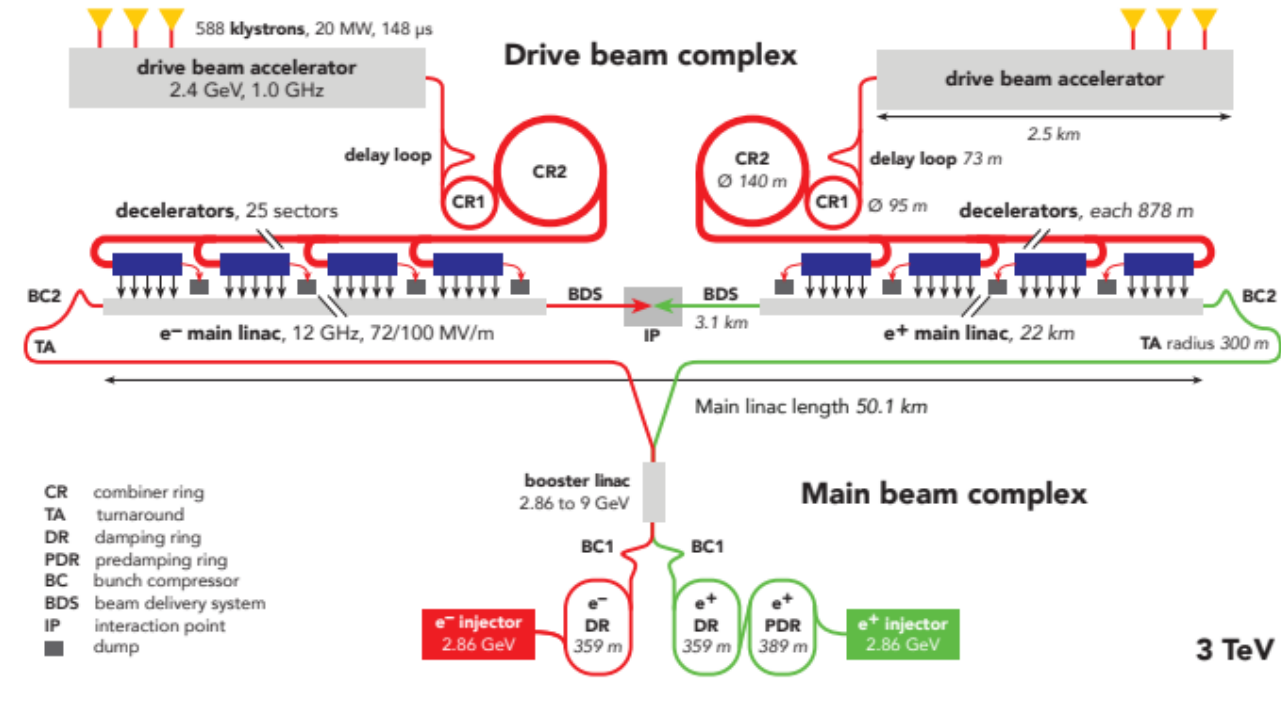


e^+e^- collisions

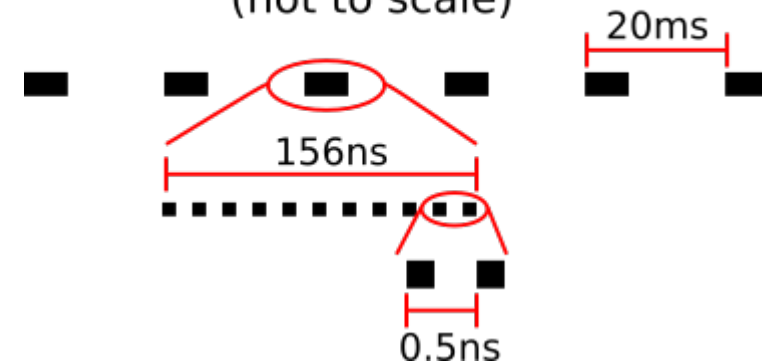
- electrons = elementary particle
 - well-defined initial state
→ allows high precision measurements
- linear collider required
→ synchrotron radiation
- cleaner experimental environment
 - triggerless readout
 - low radiation levels
- superior sensitivity to electroweak processes

CLIC - the accelerator

- accelerating structures + magnets
 - operated at room temperature
- two-beam acceleration scheme
 - drive beam: high current, low energy
 - main beam: low current, high energy
- bunch structure:
 - low duty-cycle:
156ns/20ms $\sim 0.00078\%$
 - allows triggerless readout
+ power-cycling between bunches



beam structure @ 3TeV (not to scale)

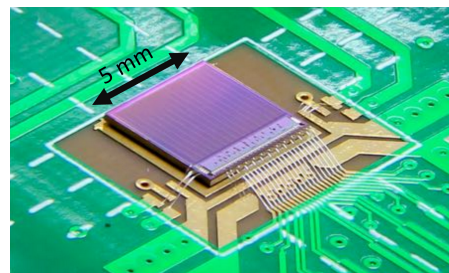
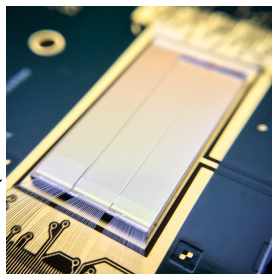


Broad Pixel Detector R&D for CLIC

Prototype Testing

- **monolithic CMOS**

- ATLASpix_simple
180nm HV CMOS process with a large collection electrode
- CLICTD
180nm CMOS imaging process with small collection electrode



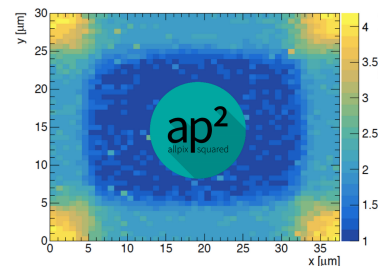
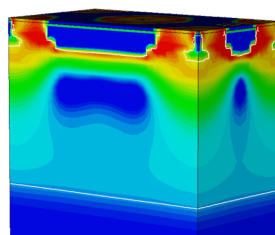
- **Silicon-on-Insulator**

- **hybrid CMOS**

- CLICpix(2)
- hybridisation methods:
 - bump bonding
 - anisotropic conductive films
 - capacitive coupling, ...

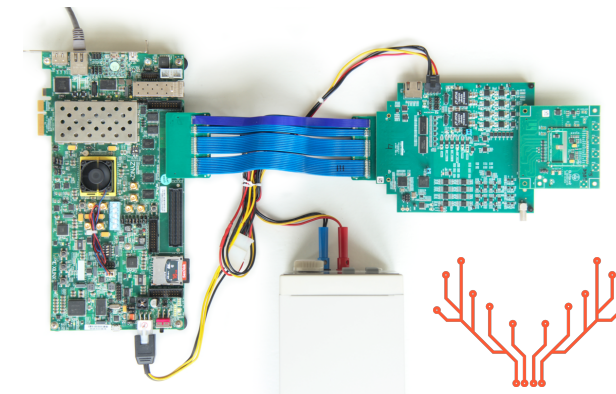
Simulations

- 3D TCAD
- high statistics Monte-Carlo



Readout Systems

- Caribou DAQ System
flexible & modular



Software

- Corryvreckan
test-beam analysis
- Allpix Squared
sensor simulation



Comparison of Pixel Sensor Technologies

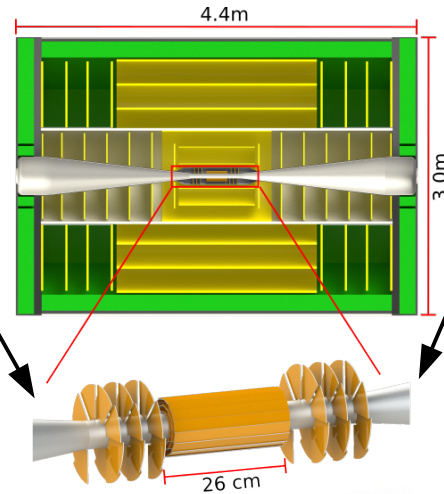
Monolithic → tracker & vertex detector?

- **advantages**

- based on commercial processes (**reduced cost**/manufacturing complexity)
- no bump bonding (expensive, difficult)
- **low material budget** (can be thinned to 50 μm)

- **challenges**

- circuitry ↔ sensor influence
- complex sensor layouts/ limited information on processing details



Hybrid → vertex detector?

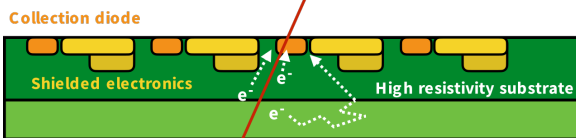
- **advantages**

- separate optimisation: sensor / readout chip

- **challenges**

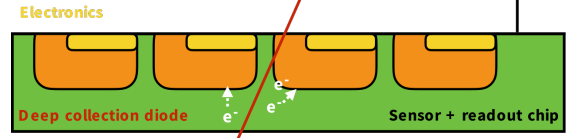
- fine pitch interconnects (yield, cost)
- material budget

small collection electrode

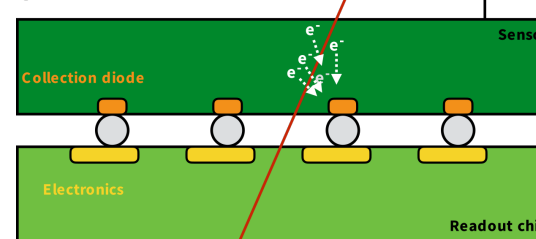


Focus of today

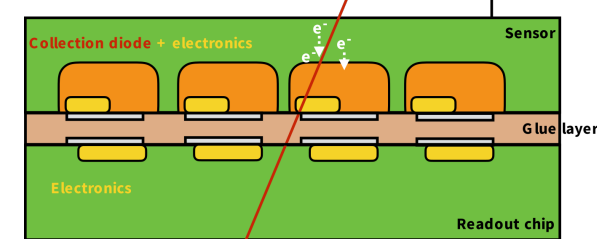
large collection electrode



bump bonded to planar sensor



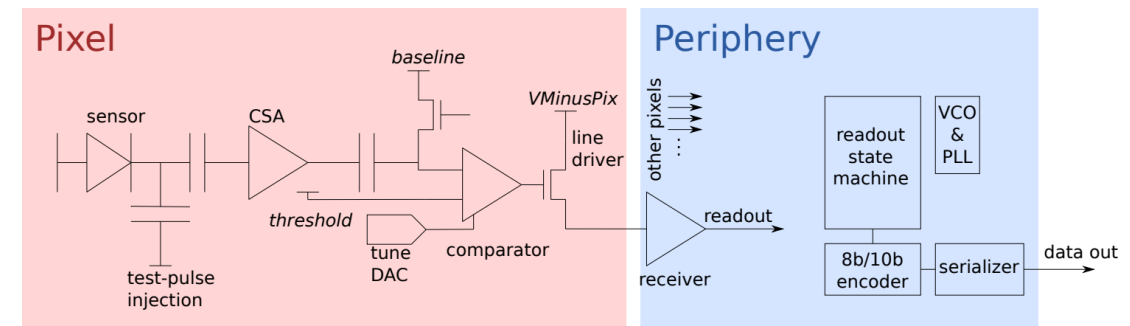
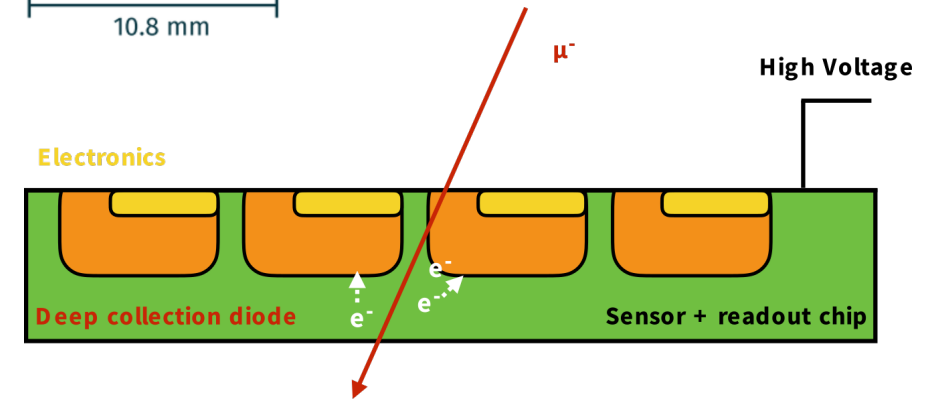
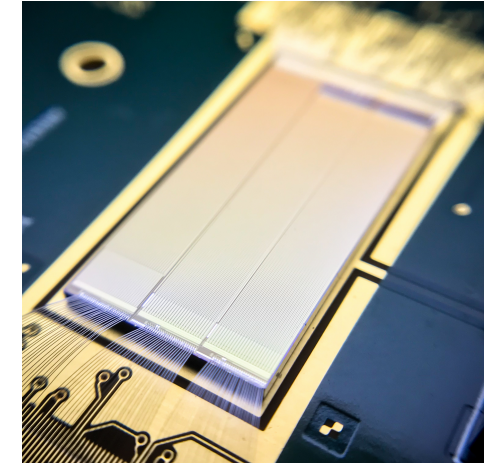
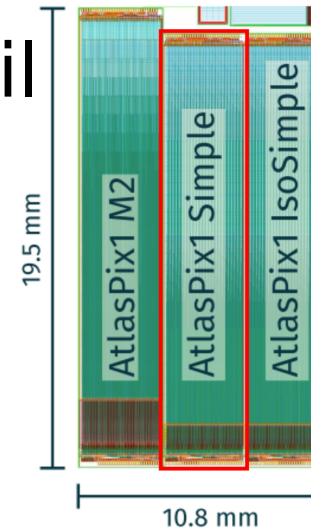
capacitively coupled to active sensor



The ATLASpix - in more detail

- **high-voltage monolithic active pixel sensor (HV-MAPS)**
- designed for ATLAS ITk upgrade
(submatrix *simple* also interesting for CLIC Tracker)
- large collection electrode

technology	AMS/TSI 180nm CMOS
readout scheme	triggerless column drain
pixel matrix	25 columns x 400 rows
pixel size	130 x 40 μm^2
time-of-arrival (hit timestamp)	10 bit, 8ns binning
time-over-threshold (charge measurement)	6 bit
substrate resistivity	20, 80, 200 Ωcm
sensor thickness	62 - 100 μm

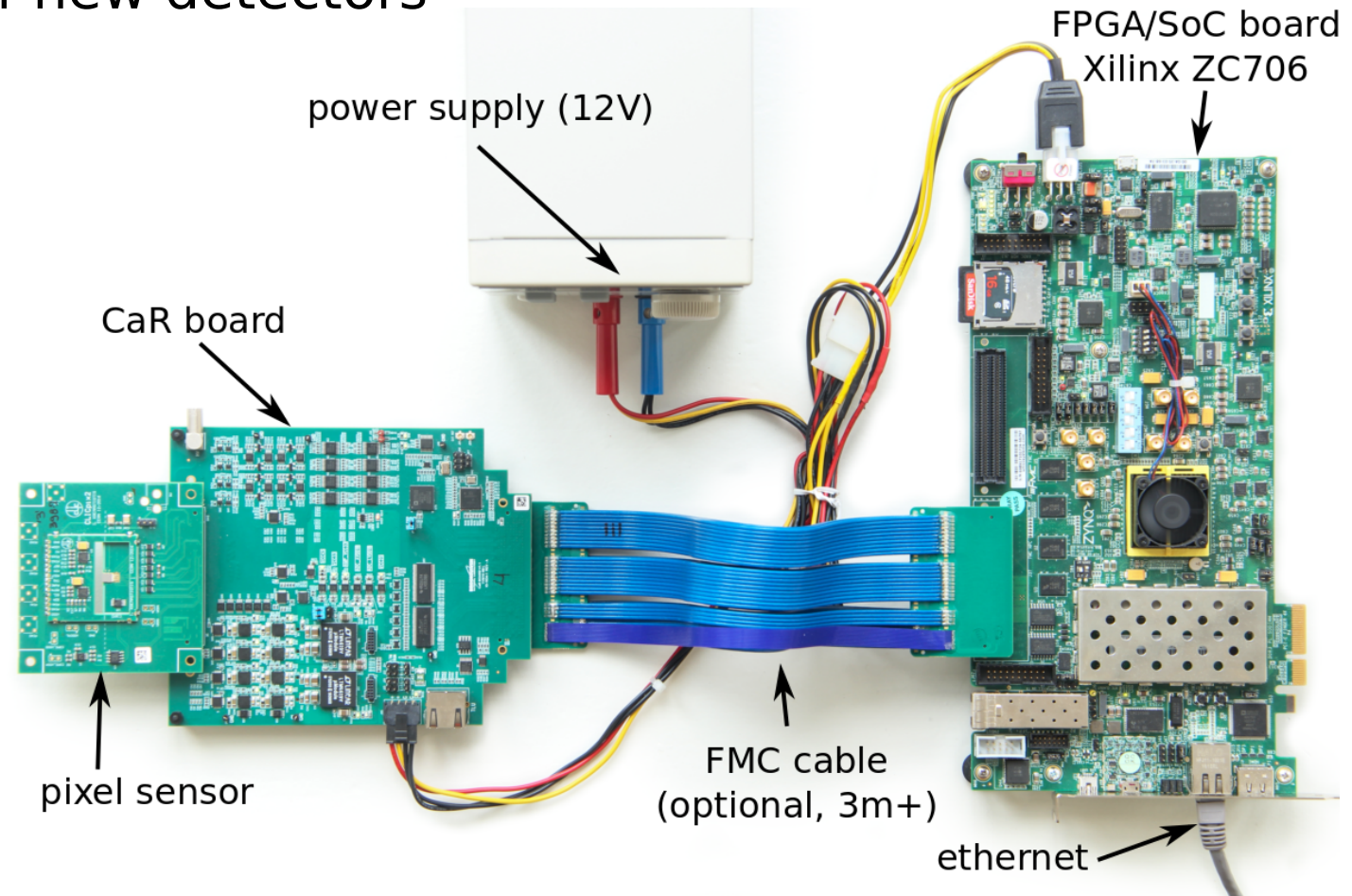
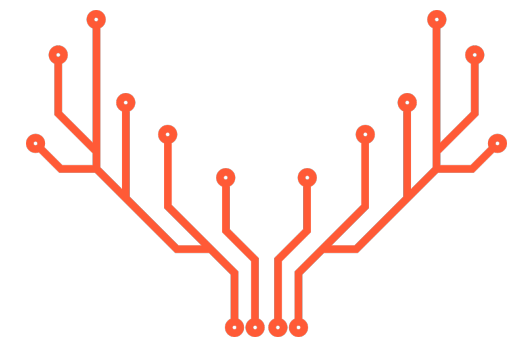


The ATLASpix - investigated samples

- w06s12:
 - resistivity $\sim 20 \Omega\text{cm}$
 - thickness = $100 \mu\text{m}$
- w10s30:
 - resistivity $\sim 80 \Omega\text{cm}$
 - thickness = **$62 \mu\text{m}$**
- w23s11:
 - resistivity $\sim 200 \Omega\text{cm}$
 - thickness = $100 \mu\text{m}$
- w10s30 is thinner than the other 2 samples
 - no $80 \Omega\text{cm}$ sample available with $100 \mu\text{m}$
 - expect no effect on performance:
active depth/depletion depth $< 50 \mu\text{m}$

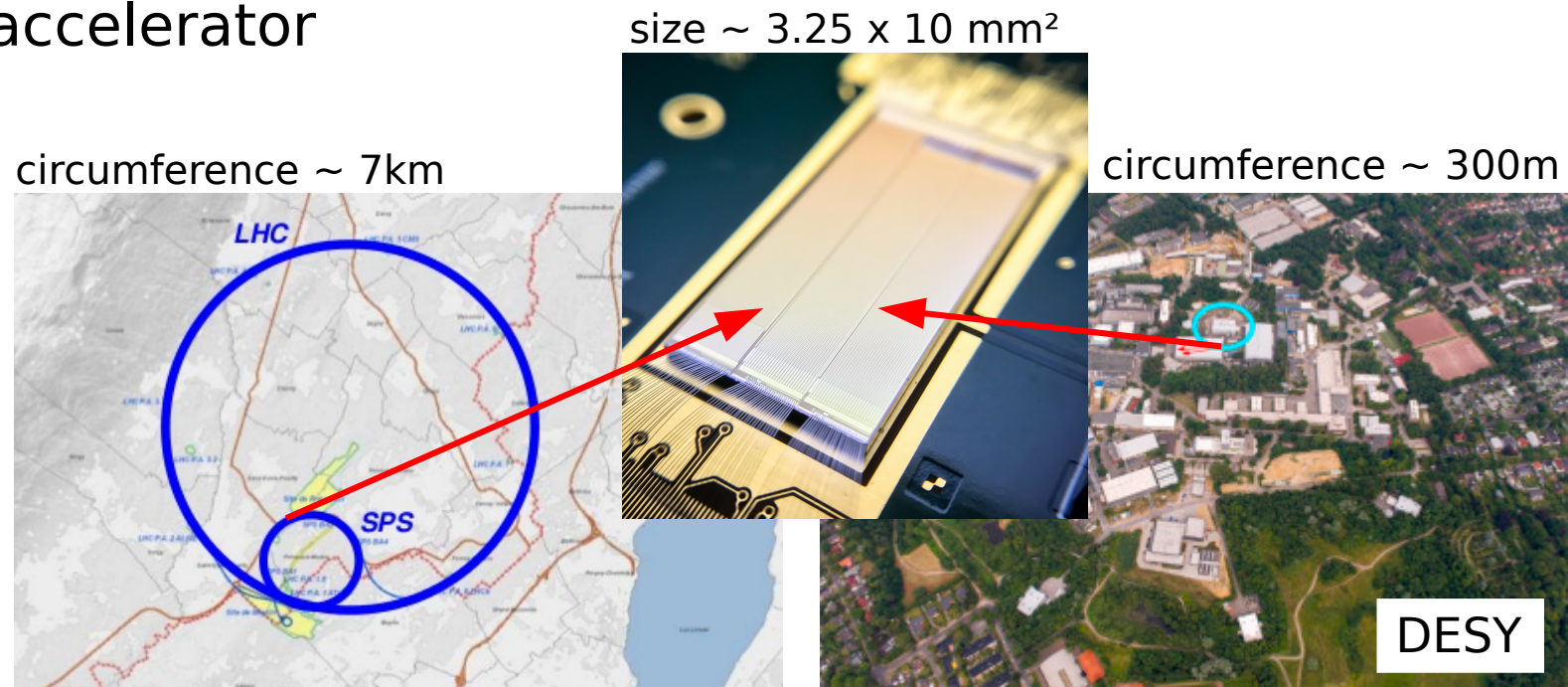
Caribou - the readout system

- versatile, open-source, linux-based
- fast & simple implementation of new detectors
→ “fast prototyping”
- **universal:**
 - FPGA board
 - Control & Readout (CaR) board
 - “most of the” firmware/software
- **chip-specific:**
 - chip board
 - “some” firmware/software blocks



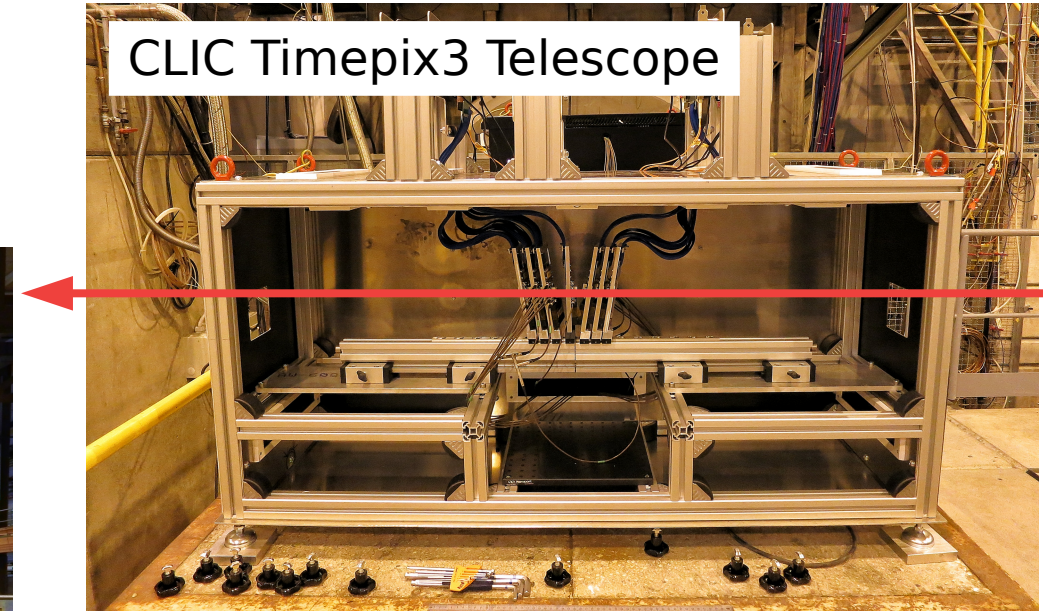
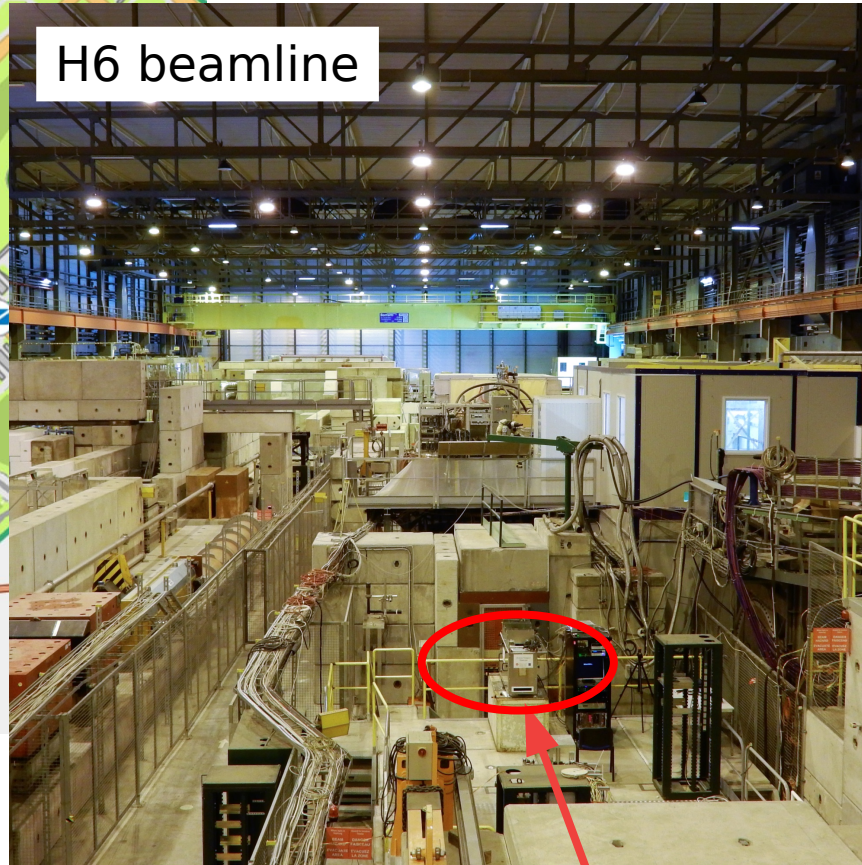
How to characterize a pixel sensor?

- need **ionizing particles**
- need **reference (position, time)** with higher precision than device-under-test
- **particle beams** from an accelerator
 - SPS @ CERN
 - DESY II @ DESY
- **beam telescope** for tracking

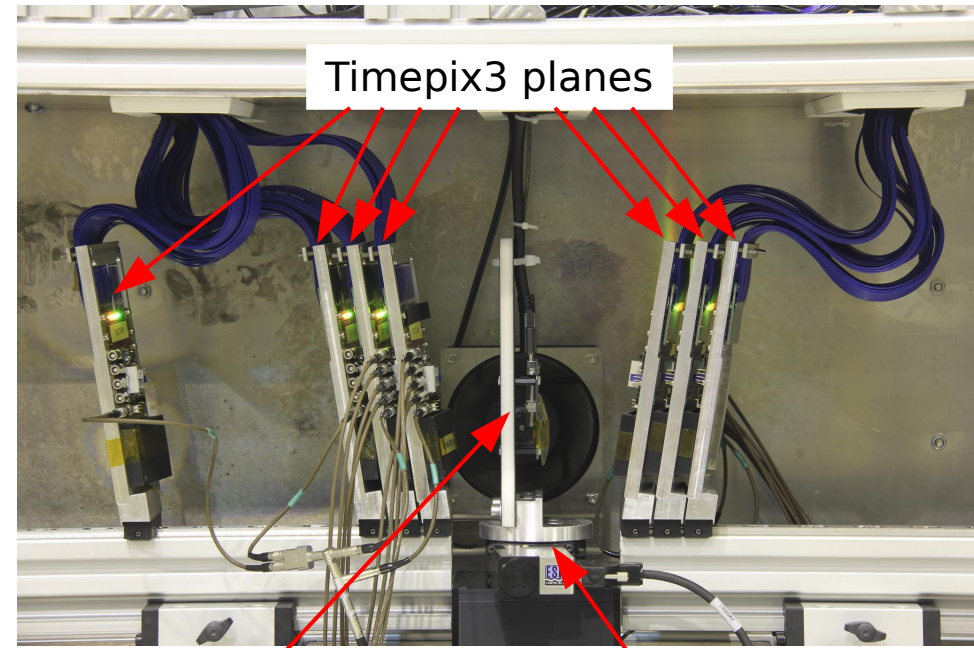
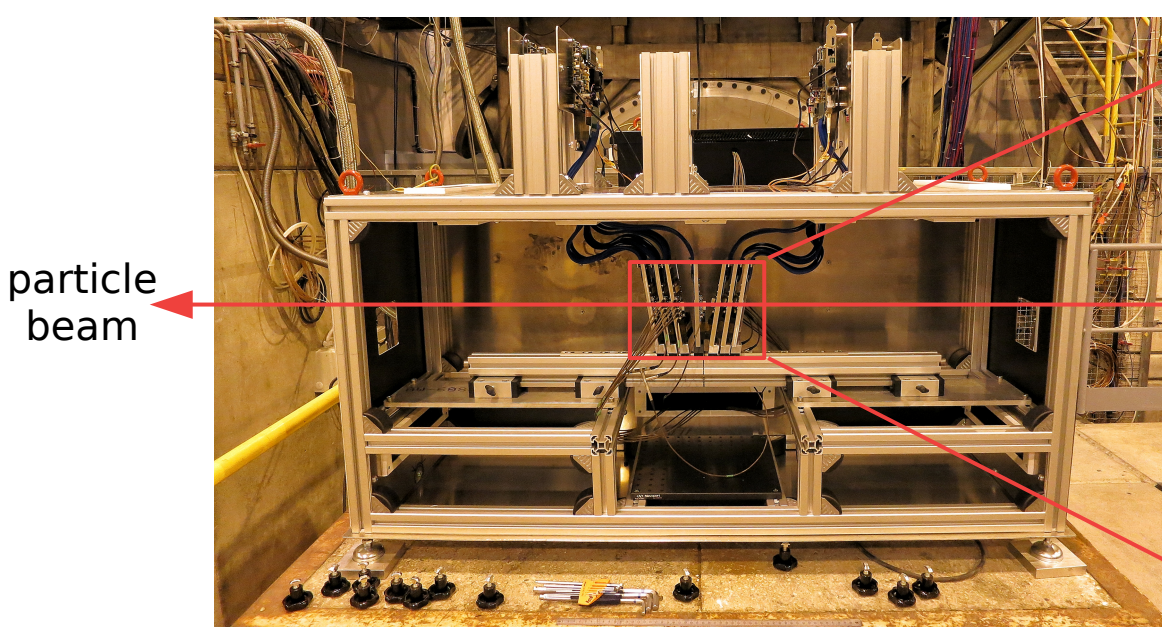


from <https://www.slideshare.net/SparkSummit/the-next-cern-accelerator-logging-service-a-road-to-big-data-with-jakub-wozniak-cern> from <https://doi.org/10.1016/j.nima.2018.11.133>

SPS at CERN - a look into the North Area beam lines

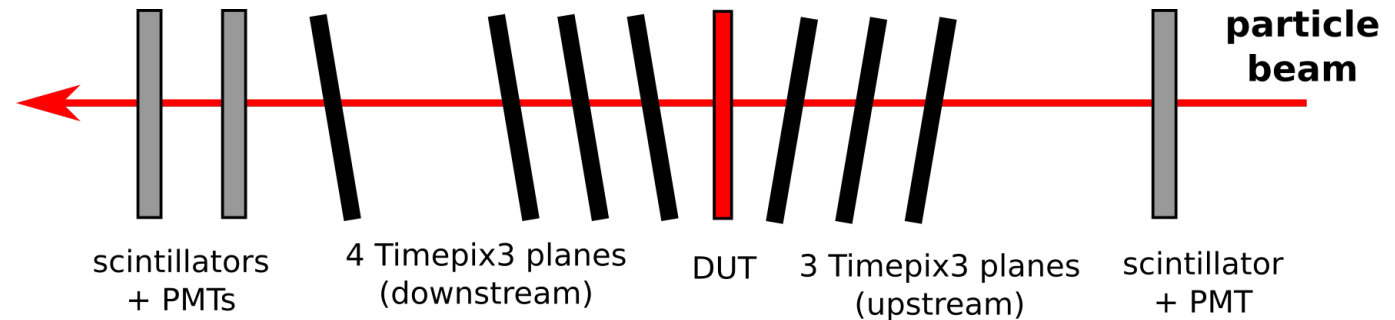


Beam Telescope - providing the reference tracks



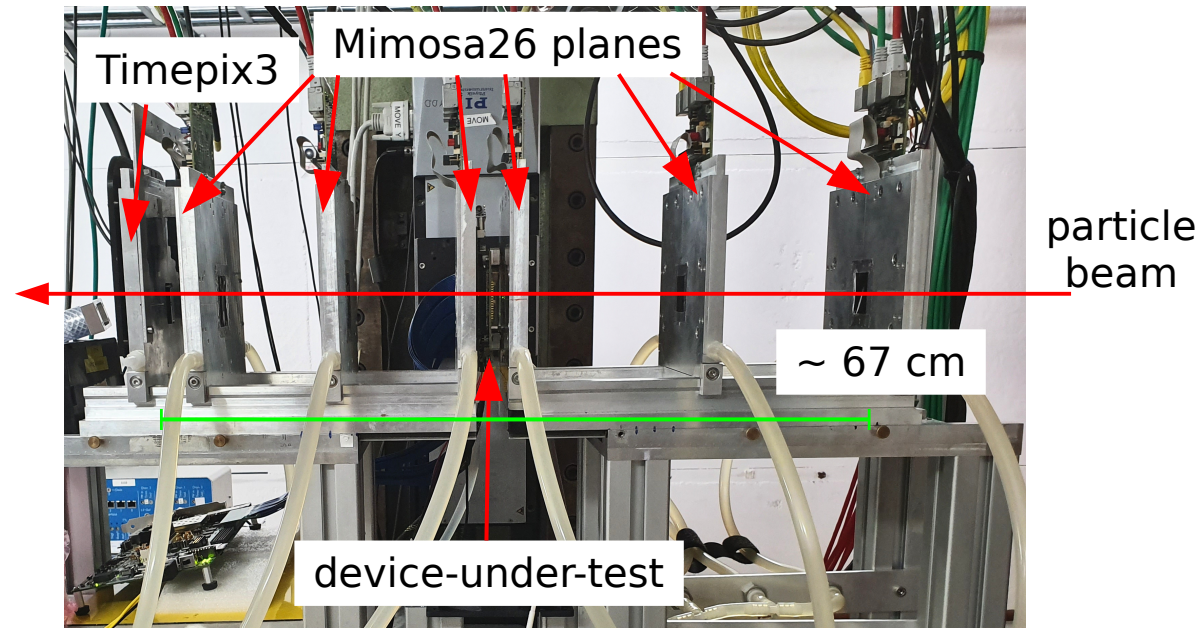
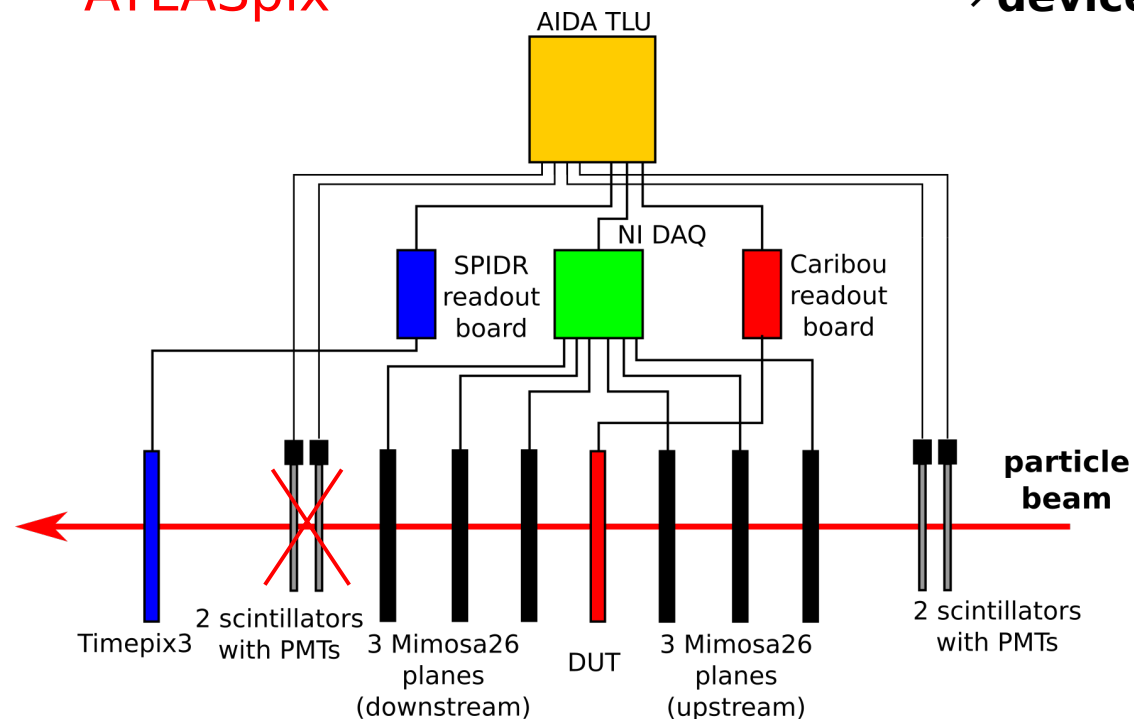
device-under-test (DUT) translation + rotation stage

- typical beam condition at **SPS**:
 - pions with ~ 120 GeV
 - rate of ~ 1 MHz
(1 spill of 4.8s/50s super-cycle)



Test Beam Setup at DESY

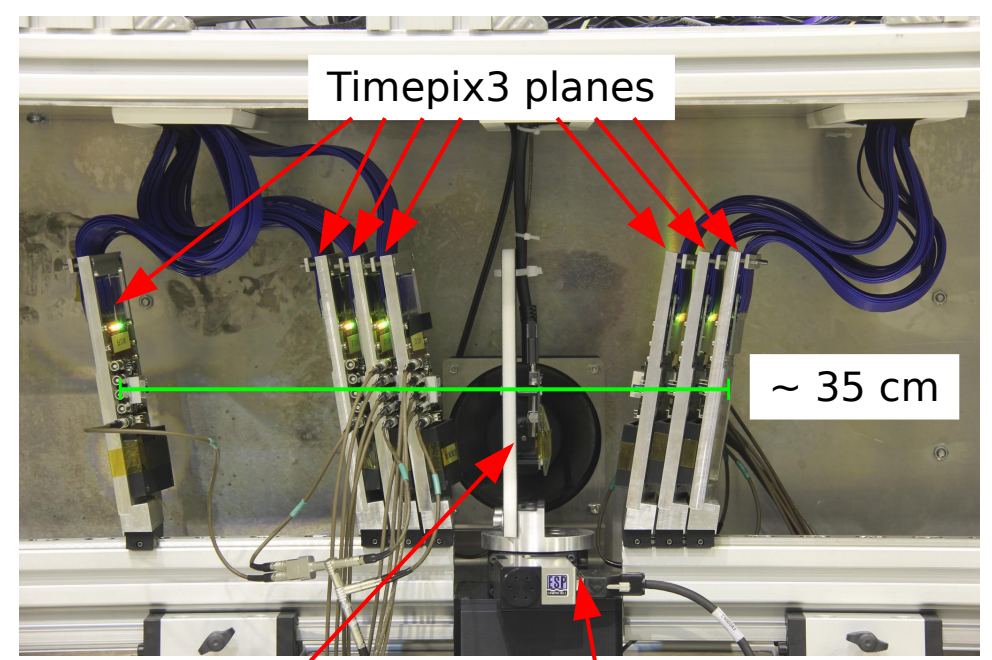
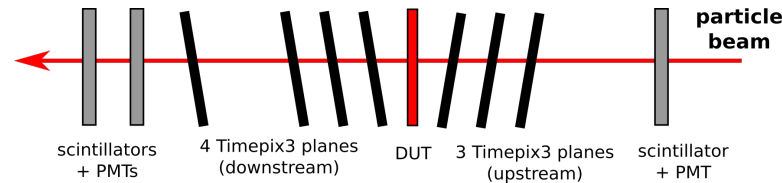
- **AIDA Trigger Logic Unit (TLU)** → provides **global clock** (time sync.) + **triggers** Mimosa Readout
- 2-3 scintillators + PMTs → input to TLU
- 6 Mimosa26 planes → good **spatial resolution**, “no” timing (2x 115 μ s bins rolling shutter)
- **Timepix3** → nanosecond **track timestamps**
- **ATLASpix** → **device-under-test** (DUT)



SPS vs. DESY II

SPS:

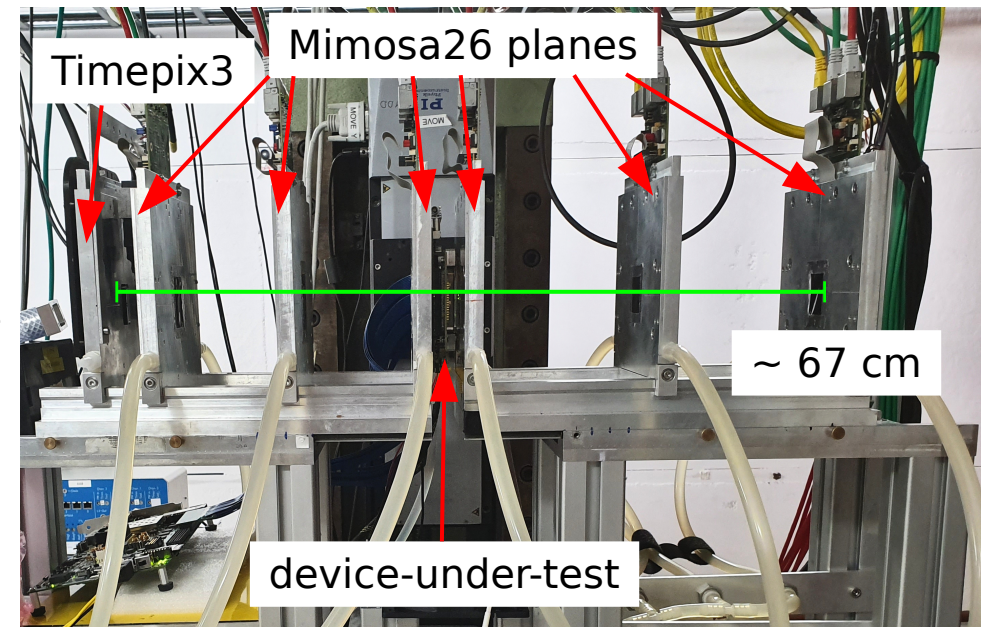
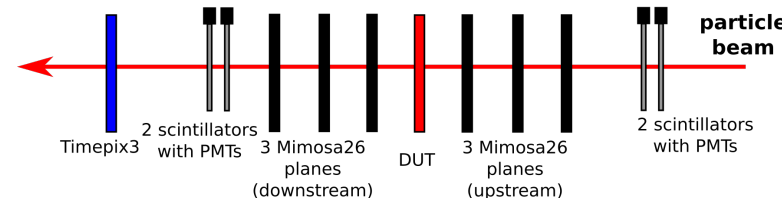
- typical beam condition:
120 GeV pions @ few MHz
- telescope in operation
2014-2018



device-under-test translation + rotation stage

DESY:

- typical beam condition:
5.4 GeV electrons @ few kHz
- use for CLICdp testbeam
campaigns during
LHC LS2 2019-2020



device-under-test

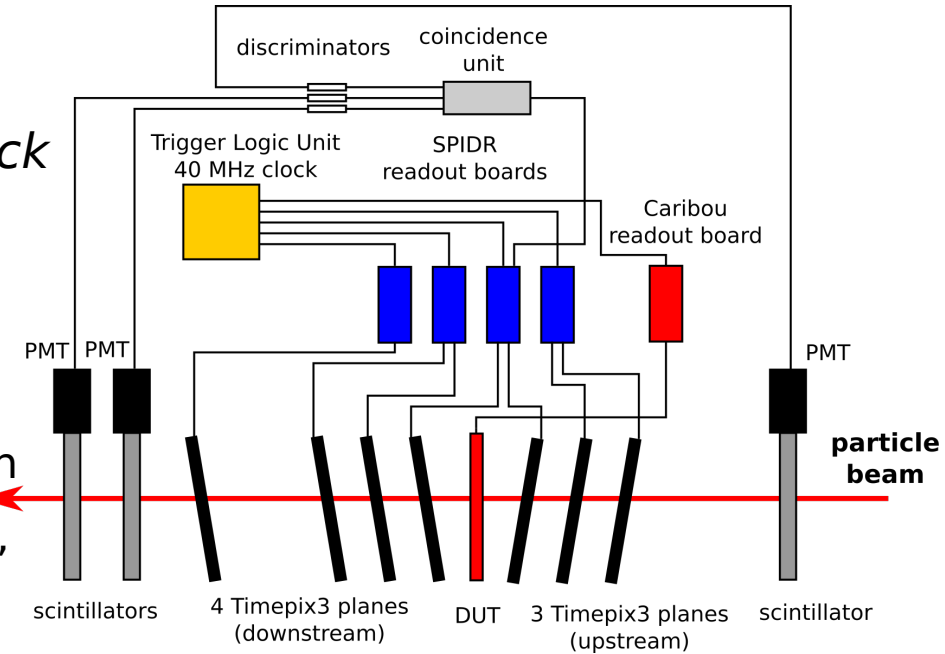
→ much lower rate & energy

SPS vs. DESY II - Readout

continuous readout, timestamps synchronous with global clock

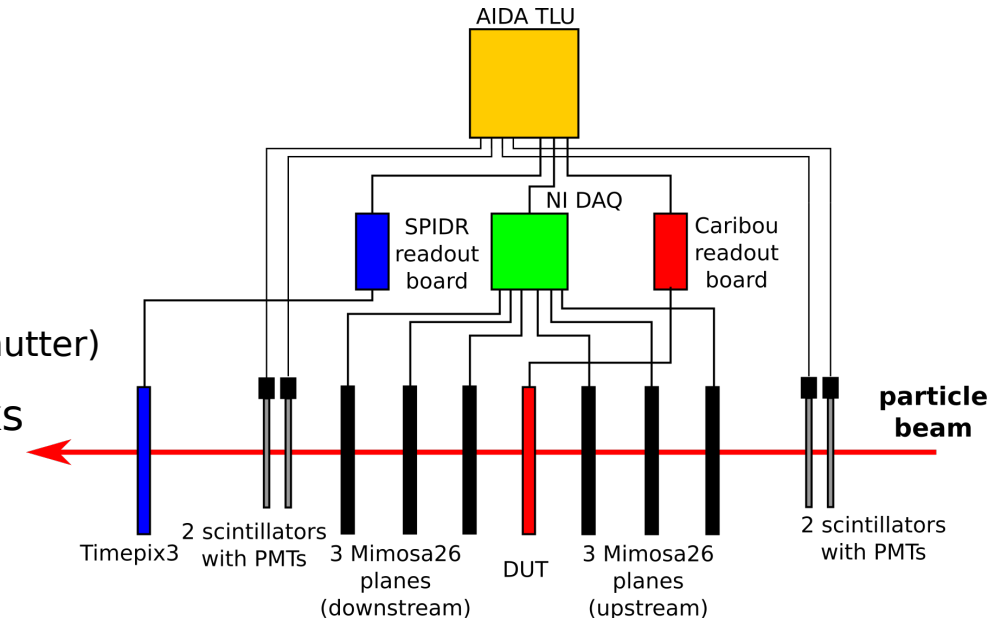
SPS:

- Trigger Logic Unit (TLU) → provides global clock (time sync.)
- 3 scintillators + PMTs → trigger timestamps
- 7 Timepix3 planes → excellent spatial + timing resolution
- DUT → Investigator, Cracow SOI, Timepix3, CLICpix, CLICpix2, **ATLASpix**



DESY:

- AIDA TLU → provides global clock (time sync.) + triggers Mimosa Readout
- 4 scintillators + PMTs → input to TLU
- 6 Mimosa26 planes → good spatial res. (2x 115μs bins rolling shutter)
- Timepix3 → used to assign ns timestamp to tracks
- DUT → CLICpix2, **ATLASpix**, CLICTD



→ **additional subsystem**

SPS vs. DESY II - Changes in the Analysis

Tracking:

- **SPS:**

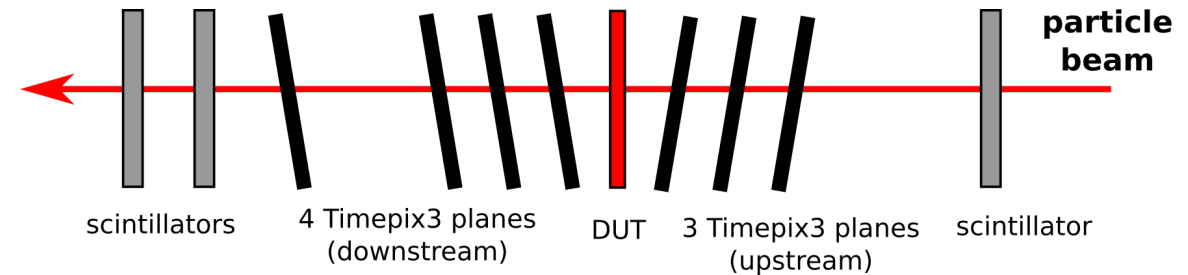
- 7 Timepix3 hits with precise timestamp
- track timestamp = average TPX3 timestamp

- **DESY:**

- Mimosa26 hits (3x 115 μ s) with multiple trigger timestamps
- require Timepix3 for unambiguous track time
- track timestamp = TPX3 timestamp

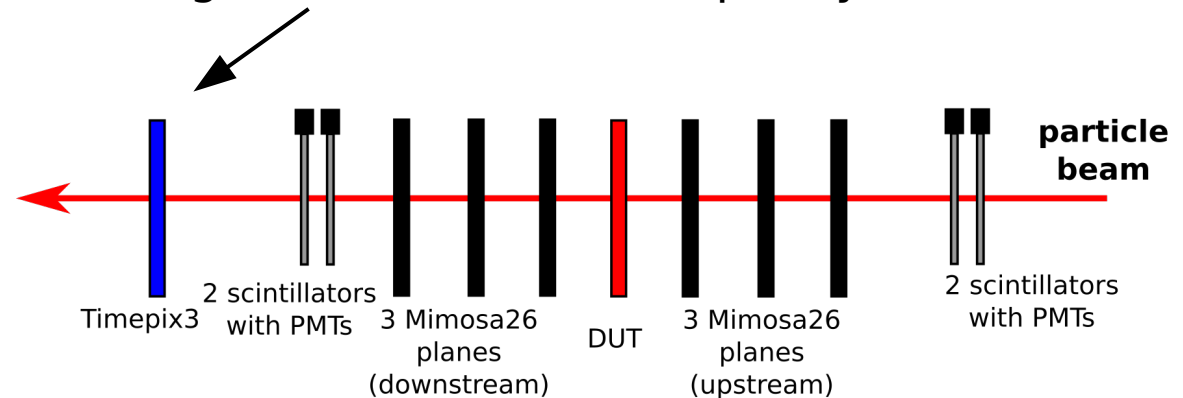
SPS:

all sensors provide hit timestamps for tracking



DESY:

unambiguous track timestamp only with TPX3



Test-beam Analysis for Pixel Sensors

Challenge:

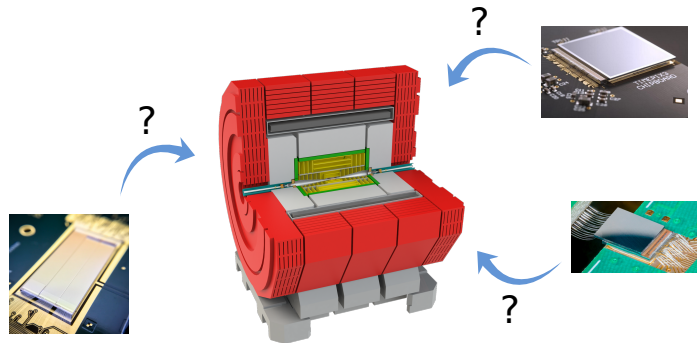


LHC upgrades + future HEP experiments:

- stringent detector requirements
- pushing limits of technology

→ R&D on vast range of pixel detector technologies

- different readout concepts
- highly specialized to each use case



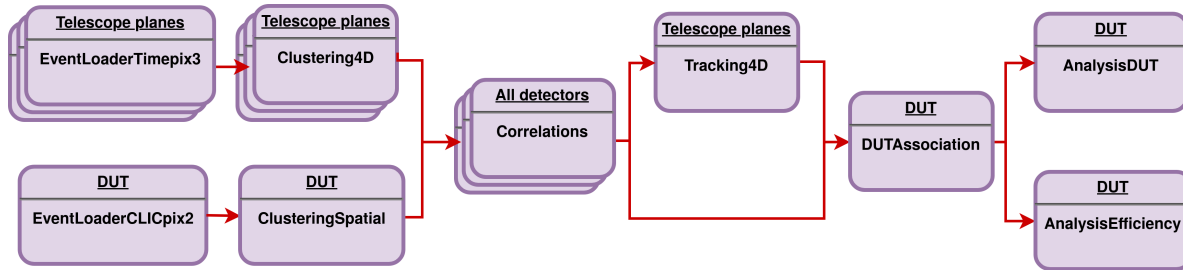
Our Motivation:

- maximize synergies
 - avoid numerous similar frameworks
 - "one framework fits all"
- flexible reconstruction
 - combine detectors with different read-out schemes
 - different analysis objectives
- easy to use, understand, contribute



The Corryvreckan Framework

- modular structure
 - framework core
 - (user) modules for specific tasks
- clean code & documentation
 - modern C++, code reviews, CI
 - comprehensive user manual (> 100 pages!)





- highly flexible and configurable
 - TOML style = easy to read
 - support of physical units (e.g. 25um)

```
1 [Corryvreckan]
2 log_level = "WARNING"
3 detectors_file = "geometry.conf"
4 number_of_tracks = 900000
5
6 [EventLoaderEUDAQ2]
7 file_name = "data/run0000456.raw"
8 inclusive = false
9 buffer_depth = 1000
10 shift_triggers = -1
```

```
1 [W0013_D04]
2 number_of_pixels = 256, 256
3 orientation = 10.9deg, 17.2deg, -1.3deg
4 orientation_mode = "xyz"
5 pixel_pitch = 55um, 55um
6 position = 886.5um, 270um, 0
7 spatial_resolution = 4.8um, 4.8um
8 time_resolution = 1.56ns
9 type = "Timepix3"
10 role = "reference"
```

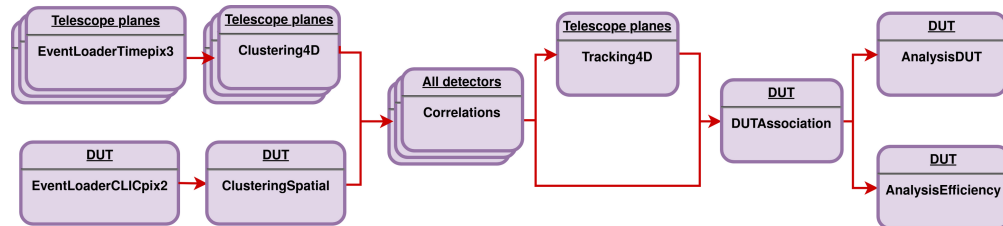
Some Notable Features:

- 4D tracking (spatial + time cuts)
- various alignment methods (track χ^2 , Millepede)
- General Broken Line (GBL) track reconstruction (multiple Coulomb scattering)
-  integration <https://github.com/eudaq/eudaq/>
 - include **AIDA TLU** as auxiliary device
 - process data recorded with **EUDAQ2 DAQ**
- job submission tool (HTCondor etc.)
- read in simulated data from **Allpix Squared** <https://cern.ch/allpix-squared> 

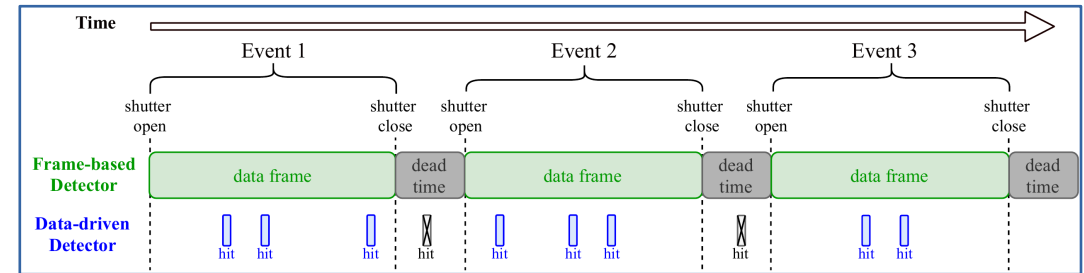
Combining Different Readout Schemes

- event building:
arrange data from different devices in
“**time slices**” (events) for reconstruction/analysis
- flexible:
combine devices with different readout schemes
 - frame-based,
 - data-driven,
 - triggered,
 - ...

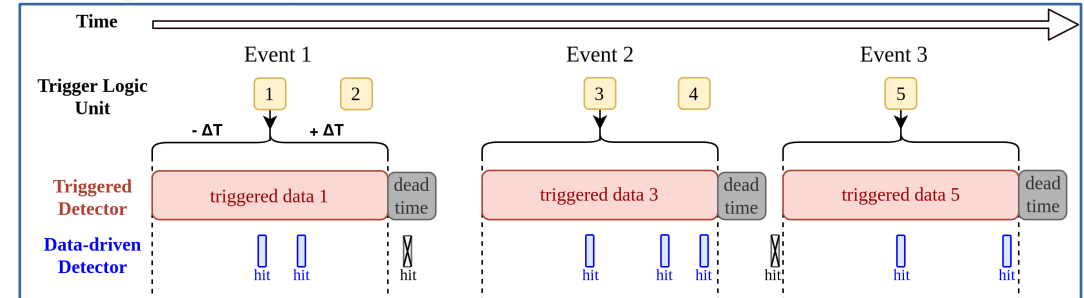
→ full analysis chain event-by-event



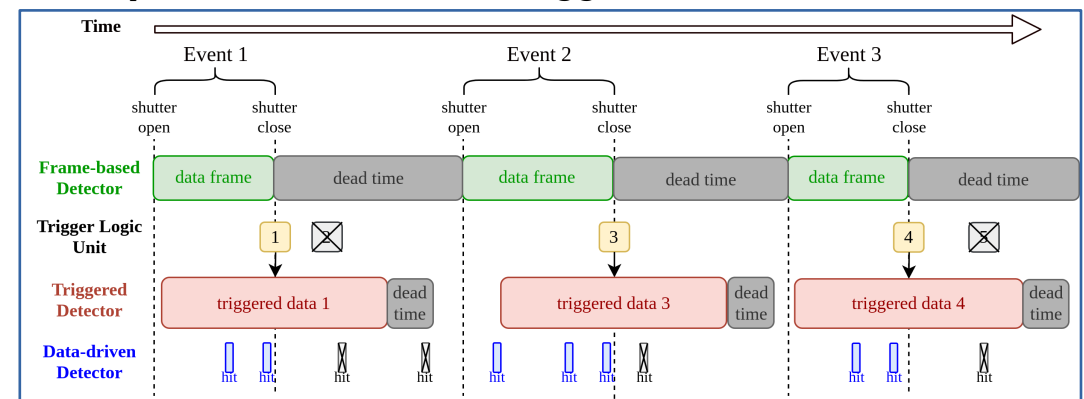
Example 1: frame-based + data-driven detectors



Example 2: triggered + data-driven detectors



Example 3: frame-based + triggered + data-driven detectors



Corryvreckan in short

reconstruction and analysis tool

for pixel detector test beam data

- highly flexible/configurable
 - separate modules for each reconstruction/analysis step
 - many different event building options
- comprehensive documentation + beginner-friendly tutorials
- growing number of users + contributors

Learn more:



Visit our website:

<https://cern.ch/corryvreckan>



Browse through our manual:

→ [Get the latest version here](#)



Try our tutorials:

→ [Get Started](#) (no prior experience required)

→ [Advanced](#) (more complex use cases)



Check out the repository:

<https://gitlab.cern.ch/corryvreckan/corryvreckan>



Discuss in the forum:

<https://corryvreckan-forum.web.cern.ch/>



Contact us:

corryvreckan.info@cern.ch

<https://mattermost.web.cern.ch/corryvreckan>

References & Repositories

- **The Compact Linear Collider (CLIC) - 2018 Summary Report**, CERN-2018-005
 - **Detector Technologies for CLIC**, CERN-2019-001
 - **ATLASpix**: doi:<https://doi.org/10.1016/j.nima.2018.06.060>
 - **CLICTD**: doi:<https://doi.org/10.22323/1.343.0072>
 - **Cracow SOI**: doi:<https://doi.org/10.1016/j.nima.2018.06.017>
 - **Simulations**: doi: 10.1088/1748-0221/14/05/C05013, CLICdp-Pub-2019-008
-
- **Caribou**: <https://gitlab.cern.ch/Caribou/>
 - **Corryvreckan**: <https://gitlab.cern.ch/corryvreckan/corryvreckan>
 - **Allpix Squared**: <https://gitlab.cern.ch/allpix-squared/>